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- **Controlled Baseline** 
  - One Assembly/Test Site, One Fabrication
- **Extended Temperature Performance of** -55°C to 125°C
- **Enhanced Diminishing Manufacturing** Sources (DMS) Support
- **Enhanced Product-Change Notification**
- Qualification Pedigree<sup>†</sup>
- Inputs Are TTL-Voltage Compatible
- **EPIC™** (Enhanced-Performance Implanted **CMOS) Process**
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

#### D OR PW PACKAGE (TOP VIEW) 14 🛮 V<sub>CC</sub> 1CLR 1D [ 13 2CLR 1CLK [] 3 12**∏** 2D 1PRE ∏ 4 11 2CLK 1Q [ 10 2PRE 1Q 6 9 🛮 2Q GND [ 8∏2Q

### description/ordering information

The SN74AHCT74 is a dual positive-edge-triggered D-type flip-flop.

A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

### ORDERING INFORMATION

TA	PACK	AGE <sup>‡</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
5500 to 40500	SOIC - D	Tape and reel	SN74AHCT74MDREP	AHCT74MEP
–55°C to 125°C	TSSOP – PW	Tape and reel	SN74AHCT74MPWREP	AHT74EP

<sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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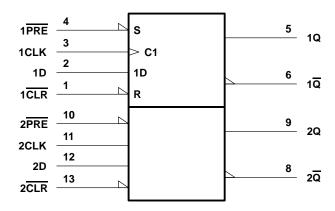
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### **FUNCTION TABLE**

	INP	UTS		OUTPUTS			
PRE	CLR	CLK	D	Q	ω		
L	Н	Х	Х	Н	L		
Н	L	X	Χ	L	Н		
L	L	X	Χ	н†	H <sup>†</sup>		
Н	Н	$\uparrow$	Н	Н	L		
Н	Н	$\uparrow$	L	L	Н		
Н	Н	L	Х	Q <sub>0</sub>	$\overline{Q}_0$		

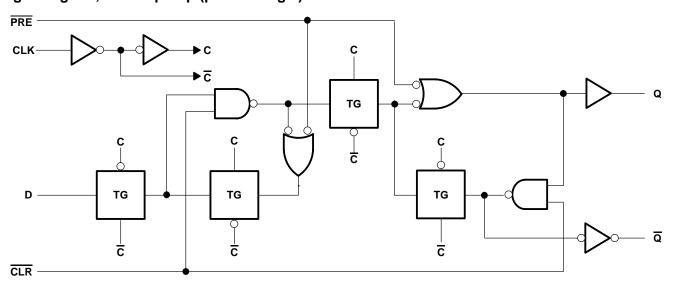
<sup>†</sup> This configuration is unstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

# logic symbol‡



<sup>&</sup>lt;sup>‡</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram, each flip-flop (positive logic)





# SN74AHCT74-EP DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH CLEAR AND PRESET

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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 7 V
Output voltage range, VO (see Note 1)	$\dots$ -0.5 V to V <sub>CC</sub> + 0.5 V
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V <sub>CC</sub> or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): D package	86°C/W
PW package	113°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
VI	Input voltage	0	5.5	V
Vo	Output voltage	0	VCC	V
ЮН	High-level output current		-8	mA
loL	Low-level output current		8	mA
Δt/Δν	Input transition rise or fall rate		20	ns/V
TA	Operating free-air temperature	-55	125	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	vcc	T,	<sub>Δ</sub> = 25°C	;	MIN	MAX	UNIT
PARAMETER	TEST CONDITIONS	vcc	MIN	TYP	MAX	IVIIIN	IVIAA	UNIT
VOH	$I_{OH} = -50 \mu A$	4.5 V	4.4	4.5		4.4		V
VOH	$I_{OH} = -8 \text{ mA}$	4.5 V	3.94			3.8		V
Voi	$I_{OL} = 50 \mu A$	4.5 V			0.1		0.1	V
VOL	$I_{OL} = 8 \text{ mA}$				0.36		0.44	
lį	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20	μΑ
Δl <sub>CC</sub> ‡	One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	5.5 V			1.35		1.5	mA
Ci	$V_I = V_{CC}$ or GND	5 V		2	10			pF

<sup>‡</sup>This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V<sub>CC</sub>.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# SN74AHCT74-EP **DUAL POSITIVE-EDGE-TRIGGERED D-TYPE FLIP-FLOP** WITH CLEAR AND PRESET

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### timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

	PARAMETER	T <sub>A</sub> = 25°C		MIN	MAX	UNIT			
	PARAMETER	MIN	MAX	IVIIIN	WAX	UNII			
	Pulse duration	PRE or CLR low	5		5		no		
t <sub>W</sub>	ruise dui ation	CLK	5		5		ns		
	Oatom Care hafare OLKA	Data					20		
t <sub>su</sub>	Setup time before CLK↑	PRE or CLR inactive	3.5		3.5		ns		
t <sub>h</sub>	Hold time, data after CLK↑		0		0		ns		

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	ТО	LOAD	T,	<b>Վ = 25°</b> C	;	MIN	MAX	UNIT
FARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIV	IVIAA	ONIT
4			C <sub>L</sub> = 15 pF	100	160		80		MHz
fmax			C <sub>L</sub> = 50 pF	80	140		65		IVITIZ
<sup>t</sup> PLH	<u> </u>	Q or Q	C <sub>I</sub> = 15 pF		7.6	10.4	1	12	ns
<sup>t</sup> PHL	PRE or CLR	Q or Q	OL = 13 pi		7.6	10.4	1	12	115
<sup>t</sup> PLH	CLK	Q or Q	C <sub>L</sub> = 15 pF		5.8	7.8	1	9	ns
<sup>t</sup> PHL	OLK	QOIQ	OL = 13 μr		5.8	7.8	1	9	113
<sup>t</sup> PLH	PRE or CLR	Q or Q	C <sub>L</sub> = 50 pF		8.1	11.4	1	13	ns
<sup>t</sup> PHL	PRE OF CLR	Q or Q	OL = 30 pr		8.1	11.4	1	13	115
<sup>t</sup> PLH	CLK	Q or $\overline{\mathbb{Q}}$	C <sub>L</sub> = 50 pF		6.3	8.8	1	10	ne
tPHL	CLK	QUQ	OL = 30 pr		6.3	8.8	1	10	ns

# noise characteristics, $V_{CC} = 5 \text{ V}$ , $C_L = 50 \text{ pF}$ , $T_A = 25^{\circ}\text{C}$ (see Note 4)

	PARAMETER	MIN	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic V <sub>OL</sub>		0.8	V
V <sub>OL(V)</sub>	Quiet output, minimum dynamic V <sub>OL</sub>		-0.8	V
VOH(V)	Quiet output, minimum dynamic V <sub>OH</sub>	4		V
V <sub>IH(D)</sub>	High-level dynamic input voltage	2		V
V <sub>IL(D)</sub>	Low-level dynamic input voltage		8.0	V

NOTE 4: Characteristics are for surface-mount packages only.

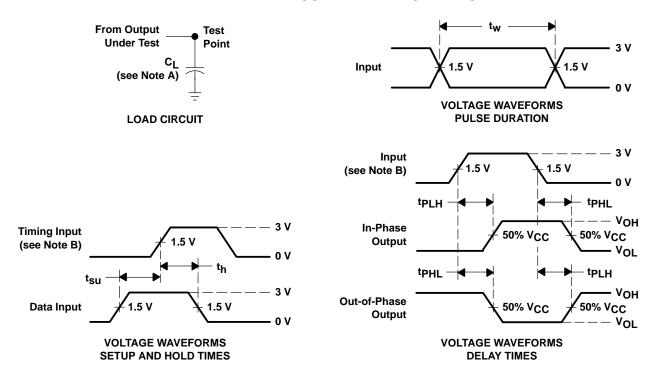
# operating characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$

Ì		PARAMETER	TEST CC	NDITIONS	TYP	UNIT
	C <sub>pd</sub>	Power dissipation capacitance	No load,	f = 1 MHz	32	pF



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### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 3 \text{ ns}$ .
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHCT74MDREP	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT74MEP	Samples
SN74AHCT74MPWREP	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHT74EP	Samples
V62/03659-01XE	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHT74EP	Samples
V62/03659-01YE	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-55 to 125	AHCT74MEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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# **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF SN74AHCT74-EP:

■ Catalog: SN74AHCT74

Military: SN54AHCT74

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# PACKAGE MATERIALS INFORMATION

www.ti.com 31-Oct-2015

## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT74MDREP	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHCT74MPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

www.ti.com 31-Oct-2015



### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT74MDREP	SOIC	D	14	2500	333.2	345.9	28.6
SN74AHCT74MPWREP	TSSOP	PW	14	2000	367.0	367.0	35.0

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